

CDSW16-G

High Speed RoHS Device Features

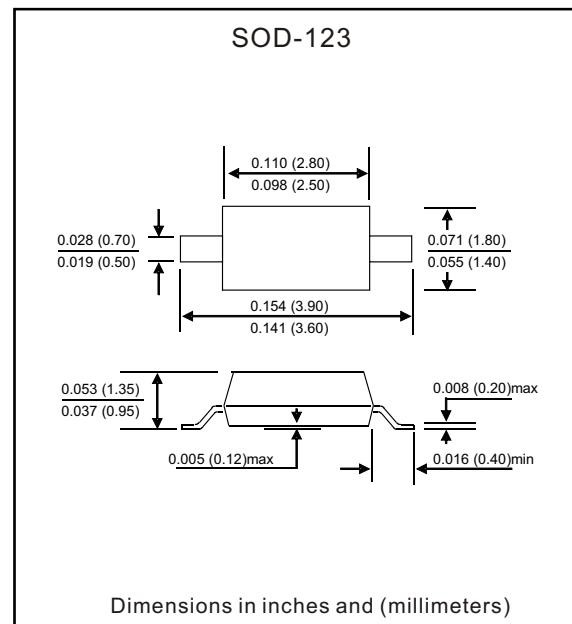
- Fast Switching Speed
- Electrically Identical to Standard JEDEC
- High Conductance
- Surface Mount Package Ideally Suited for Automatic Insertion
- Flat Package SOD-123 instead of mini-MELF Package

Mechanical data

Case: SOD-123, Molded Plastic

Terminals: Solderable per MIL-STD-202, Method 208

Weight: 0.01 gram(approx.).



Dimensions in inches and (millimeters)

Maximum Rating (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Max	Unit
Non-Repetitive peak reverse voltage		V _{RM}		100	V
Peak repetitive peak reverse voltage Working peak reverse voltage DC blocking voltage		V _{RRM} V _{RWM} V _R		75	V
RMS reverse voltage		V _{R(RMS)}		53	V
Forward continuous current		I _{FM}		300	mA
Average rectified output current		I _O		150	mA
Peak forward surge current	T _P = 1μS T _P = 1S	I _{FSM}		2 1	A
Power dissipation		P _D		400	mW
Thermal Resistance (Junction to ambient)		R _{θJA}		315	°C/W
Storage temperature		T _{STG}	-65	+150	°C
Junction temperature		T _j		+125	°C

Electrical Characteristics (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	I _F = 1 mA DC I _F = 10 mA DC I _F = 50 mA DC I _F = 150 mA DC	V _F			0.715 0.855 1.0 1.25	V
Reverse current	V _R = 20 V V _R = 75 V	I _R			25 1	nA uA
Capacitance between terminals	f = 1 MHz, and 0VDC reverse voltage	C _T			2	pF
Reverse recovery time	I _F = I _R = 10 mA, R _L = 100 ohms, I _{rr} = 0.1 × I _R	T _{RR}			4	nS

Typical Characteristics (CDSW16-G)

Fig. 1 - Forward Characteristics

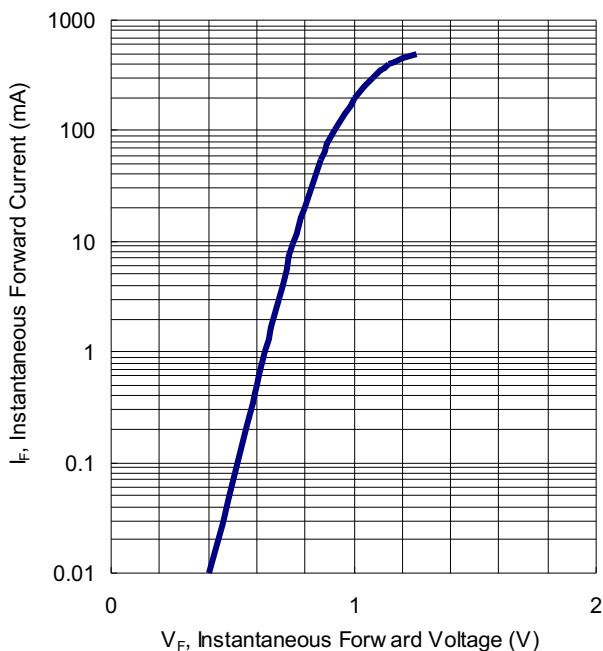


Fig. 2 - Leakage current V.S. Junction Temperature

